

# Common Anode Silicon Dual Switching Diodes

## DAP222, DAP202U

These Common Anode Silicon Epitaxial Planar Dual Diodes are designed for use in ultra high speed switching applications. The DAP222 device is housed in the SC-75/SOT-416 package which is designed for low power surface mount applications, where board space is at a premium. The DAP202U device is housed in the SC-70/SOT-323 package.

### Features

- Fast  $t_{rr}$
- Low  $C_D$
- NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPA Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

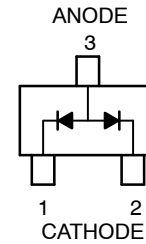
### MAXIMUM RATINGS ( $T_A = 25^\circ\text{C}$ )

| Rating                     | Symbol       | Value | Unit |
|----------------------------|--------------|-------|------|
| Reverse Voltage            | $V_R$        | 80    | Vdc  |
| Peak Reverse Voltage       | $V_{RM}$     | 80    | Vdc  |
| Forward Current            | $I_F$        | 100   | mAdc |
| Peak Forward Current       | $I_{FM}$     | 300   | mAdc |
| Peak Forward Surge Current | $I_{FSM}(1)$ | 2.0   | Adc  |

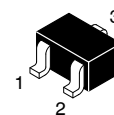
### THERMAL CHARACTERISTICS

| Rating               | Symbol    | Max             | Unit             |
|----------------------|-----------|-----------------|------------------|
| Power Dissipation    | $P_D$     | 150             | mW               |
| Junction Temperature | $T_J$     | 150             | $^\circ\text{C}$ |
| Storage Temperature  | $T_{stg}$ | $-55 \sim +150$ | $^\circ\text{C}$ |

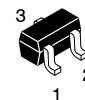
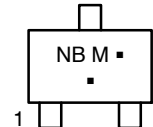
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.



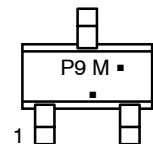
### MARKING DIAGRAMS



SC-70  
CASE 419



SC-75  
CASE 463  
STYLE 4



NB, P9 = Device Codes

M = Date Code\*

■ = Pb-Free Package

(Note: Microdot may be in either location)

\* Date Code orientation and/or orientation may vary depending upon manufacturing location.

### ORDERING INFORMATION

| Device       | Package            | Shipping†          |
|--------------|--------------------|--------------------|
| DAP222G      | SC-75<br>(Pb-Free) | 3000 / Tape & Reel |
| DAP222T1G    | SC-75<br>(Pb-Free) | 3000 / Tape & Reel |
| NSVDAP222T1G | SC-75<br>(Pb-Free) | 3000 / Tape & Reel |

### DISCONTINUED (Note 1)

|          |                    |                    |
|----------|--------------------|--------------------|
| DAP202UG | SC-70<br>(Pb-Free) | 3000 / Tape & Reel |
|----------|--------------------|--------------------|

† For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, [BRD8011/D](#).

1. **DISCONTINUED:** This device is not recommended for new design. Please contact your onsemi representative for information. The most current information on this device may be available on [www.onsemi.com](http://www.onsemi.com).

# DAP222, DAP202U

## ELECTRICAL CHARACTERISTICS ( $T_A = 25^\circ\text{C}$ )

| Characteristic                  | Symbol              | Condition                                                                                   | Min | Max  | Unit               |
|---------------------------------|---------------------|---------------------------------------------------------------------------------------------|-----|------|--------------------|
| Reverse Voltage Leakage Current | $I_R$               | $V_R = 70\text{ V}$                                                                         | –   | 0.1  | $\mu\text{A}_{dc}$ |
| Forward Voltage                 | $V_F$               | $I_F = 100\text{ mA}$                                                                       | –   | 1.2  | Vdc                |
| Reverse Breakdown Voltage       | $V_R$               | $I_R = 100\text{ }\mu\text{A}$                                                              | 80  | –    | Vdc                |
| Diode Capacitance               | $C_D$               | $V_R = 6.0\text{ V}, f = 1.0\text{ MHz}$                                                    | –   | 3.5  | pF                 |
| Reverse Recovery Time           | DAP222 $t_{rr}(2)$  | $I_F = 5.0\text{ mA}, V_R = 6.0\text{ V}, R_L = 100\text{ }\Omega, I_{rr} = 0.1\text{ }I_R$ | –   | 4.0  | ns                 |
|                                 | DAP202U $t_{rr}(3)$ | $I_F = 5.0\text{ mA}, V_R = 6.0\text{ V}, R_L = 50\text{ }\Omega, I_{rr} = 0.1\text{ }I_R$  | –   | 10.0 | ns                 |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

2.  $t = 1\text{ }\mu\text{s}$

3.  $t_{rr}$  Test Circuit for DAP222 in Figure 4.

4.  $t_{rr}$  Test Circuit for DAP202U in Figure 5.

## TYPICAL ELECTRICAL CHARACTERISTICS

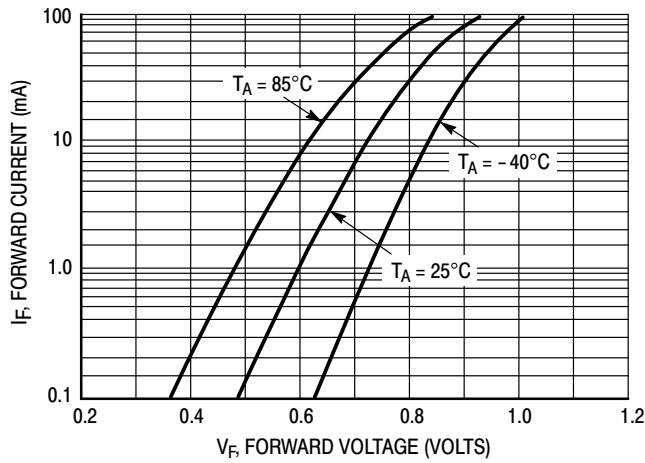


Figure 1. Forward Voltage

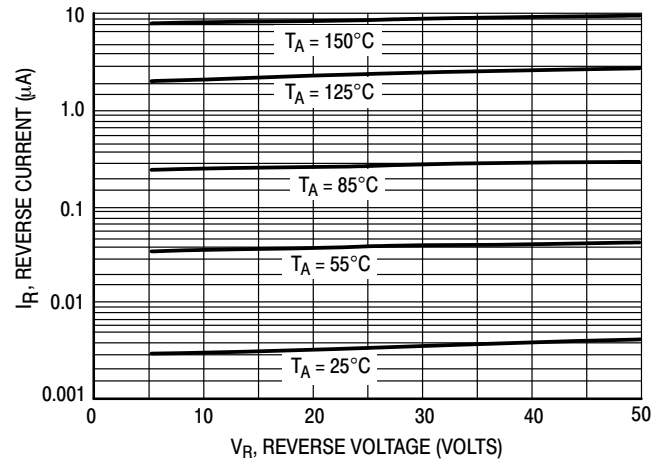


Figure 2. Reverse Current

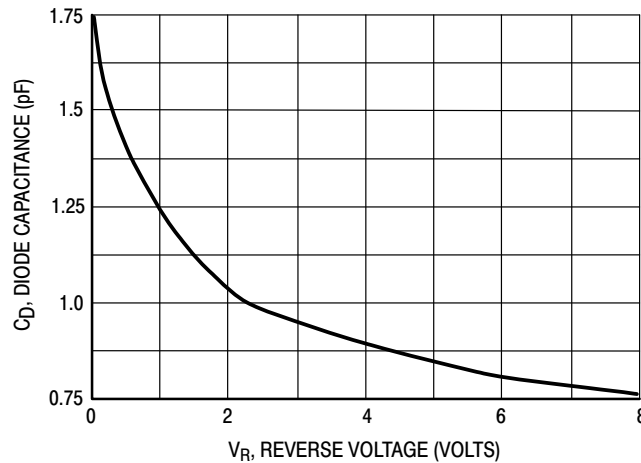
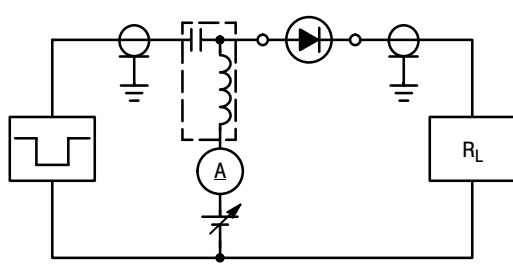
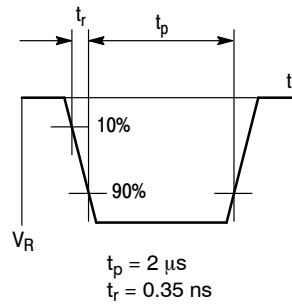


Figure 3. Diode Capacitance

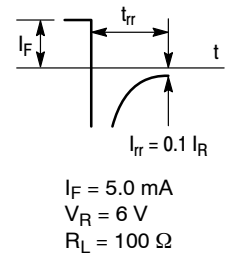
## DAP222, DAP202U



RECOVERY TIME EQUIVALENT TEST CIRCUIT

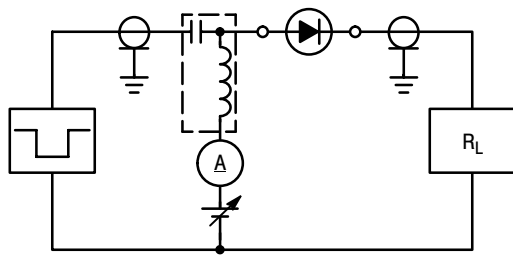


INPUT PULSE

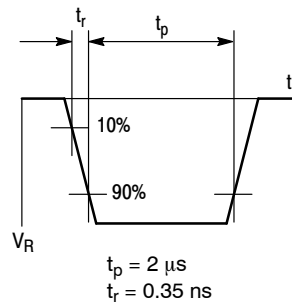


OUTPUT PULSE

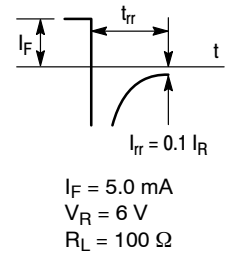
Figure 4. Reverse Recovery Time Test Circuit for the DAP222



RECOVERY TIME EQUIVALENT TEST CIRCUIT

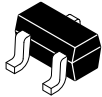


INPUT PULSE



OUTPUT PULSE

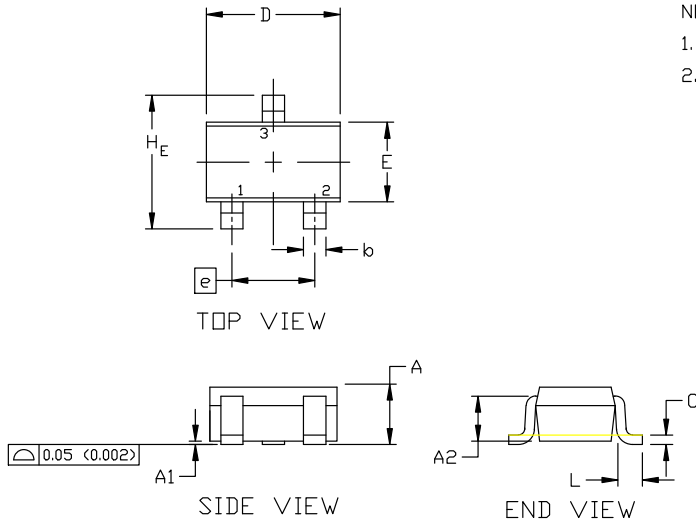
Figure 5. Reverse Recovery Time Test Circuit for the DAP202U



SCALE 4:1

SC-70 (SOT-323)  
CASE 419  
ISSUE R

DATE 11 OCT 2022

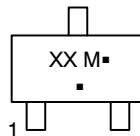


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH

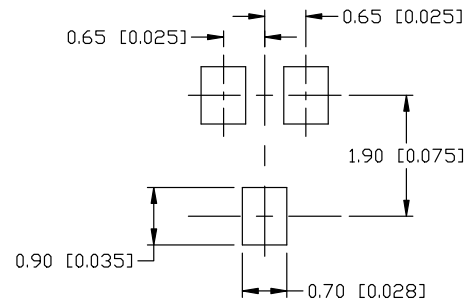
| DIM | MILLIMETERS |      |      | INCHES    |       |       |
|-----|-------------|------|------|-----------|-------|-------|
|     | MIN.        | NOM. | MAX. | MIN.      | NOM.  | MAX.  |
| A   | 0.80        | 0.90 | 1.00 | 0.032     | 0.035 | 0.040 |
| A1  | 0.00        | 0.05 | 0.10 | 0.000     | 0.002 | 0.004 |
| A2  | 0.70 REF    |      |      | 0.028 BSC |       |       |
| b   | 0.30        | 0.35 | 0.40 | 0.012     | 0.014 | 0.016 |
| c   | 0.10        | 0.18 | 0.25 | 0.004     | 0.007 | 0.010 |
| D   | 1.80        | 2.00 | 2.20 | 0.071     | 0.080 | 0.087 |
| E   | 1.15        | 1.24 | 1.35 | 0.045     | 0.049 | 0.053 |
| e   | 1.20        | 1.30 | 1.40 | 0.047     | 0.051 | 0.055 |
| e1  | 0.65 BSC    |      |      | 0.026 BSC |       |       |
| L   | 0.20        | 0.38 | 0.56 | 0.008     | 0.015 | 0.022 |
| H_E | 2.00        | 2.10 | 2.40 | 0.079     | 0.083 | 0.095 |

GENERIC  
MARKING DIAGRAM



XX = Specific Device Code  
M = Date Code  
▪ = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.



\* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

SOLDERING FOOTPRINT

STYLE 1:  
CANCELLED

STYLE 2:  
PIN 1. ANODE  
2. N.C.  
3. CATHODE

STYLE 3:  
PIN 1. BASE  
2. EMITTER  
3. COLLECTOR

STYLE 4:  
PIN 1. CATHODE  
2. CATHODE  
3. ANODE

STYLE 5:  
PIN 1. ANODE  
2. ANODE  
3. CATHODE

STYLE 6:  
PIN 1. EMITTER  
2. BASE  
3. COLLECTOR

STYLE 7:  
PIN 1. BASE  
2. EMITTER  
3. COLLECTOR

STYLE 8:  
PIN 1. GATE  
2. SOURCE  
3. DRAIN

STYLE 9:  
PIN 1. ANODE  
2. CATHODE  
3. CATHODE-ANODE

STYLE 10:  
PIN 1. CATHODE  
2. ANODE  
3. ANODE-CATHODE

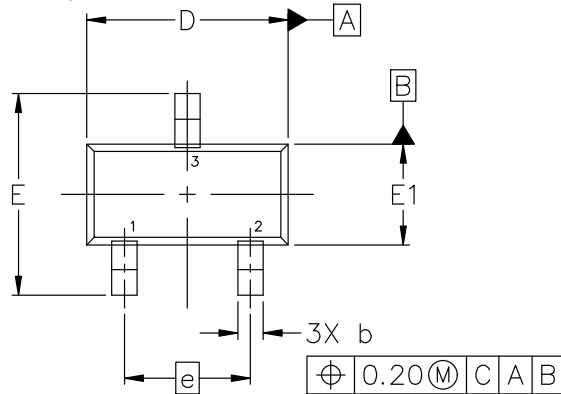
STYLE 11:  
PIN 1. CATHODE  
2. CATHODE  
3. CATHODE

|                  |                 |                                                                                                                                                                                  |
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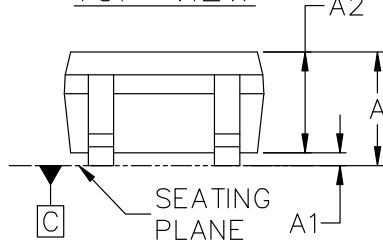
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SC75-3 1.60x0.80x0.80, 1.00P  
CASE 463  
ISSUE H

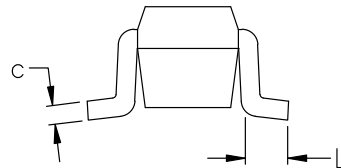
DATE 01 FEB 2024



TOP VIEW

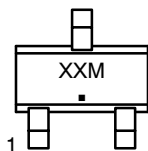


SIDE VIEW



END VIEW

GENERIC  
MARKING DIAGRAM\*



XX = Specific Device Code  
M = Date Code  
▪ = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

STYLE 1:  
PIN 1. BASE  
2. EMITTER  
3. COLLECTOR

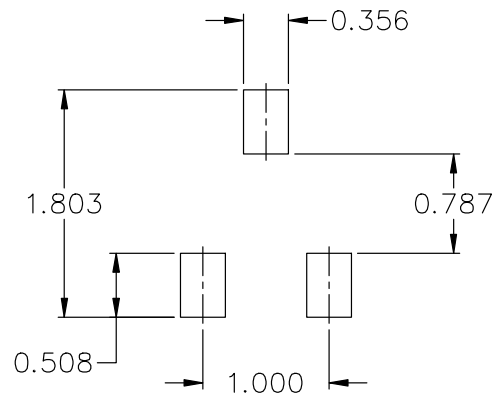
STYLE 2:  
PIN 1. ANODE  
2. N/C  
3. CATHODE

STYLE 3:  
PIN 1. ANODE  
2. ANODE  
3. CATHODE

STYLE 4:  
PIN 1. CATHODE  
2. CATHODE  
3. ANODE

STYLE 5:  
PIN 1. GATE  
2. SOURCE  
3. DRAIN

| DIM | MILLIMETERS |      |      |
|-----|-------------|------|------|
|     | MIN.        | NOM. | MAX. |
| A   | 0.70        | 0.80 | 0.90 |
| A1  | 0.00        | 0.05 | 0.10 |
| A2  | 0.80 REF.   |      |      |
| b   | 0.15        | 0.20 | 0.30 |
| c   | 0.10        | 0.15 | 0.25 |
| D   | 1.55        | 1.60 | 1.65 |
| E   | 1.50        | 1.60 | 1.70 |
| E1  | 0.70        | 0.80 | 0.90 |
| e   | 1.00 BSC    |      |      |
| L   | 0.10        | 0.15 | 0.20 |



RECOMMENDED MOUNTING FOOTPRINT\*

\* FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

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